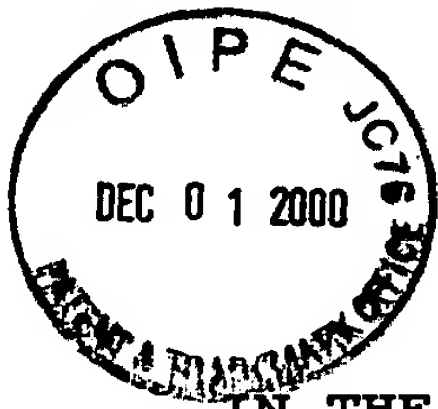


EXPRESS MAIL NO.: EL303287076US



Examiner : M. Dietrich
Art Unit : 2814
Docket No.: 52433/544

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B
Shuman
12-11-00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: K. TATSUMI et al.
Serial No.: 09/254,118 ✓
Filed : May 19, 1999 ✓
For : METHOD OF PARTIALLY PLATING SUBSTRATE FOR
ELECTRONIC DEVICES ✓

Assistant Commissioner
for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Kindly amend the claims of the above-identified
patent application as follows.

31
1-1. (Amended) A method of partially plating a substrate for electronic devices, comprising arranging (small) balls at selected portions of a substrate for mounting semiconductor devices thereon, [or a substrate for mounting electronic devices thereon and including a lead frame], and adhering or bonding the small balls thereto, and melting the small balls, thereby selectively plating the selected portions of the substrate for electronic devices with a different metal. ★

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